IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type <sup>3</sup> Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	ials and Mfg Information				
upplier	r Information															
Company name* Company unique				ique ID	e ID Uniq			Unique ID Authority					Response Date*			
nsemi												2023-06-08				
ontact Na	ame	Title - Contact			P	Phone - Contact*				Email - Contact*						
Product-E	Env-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Rep				presentative I			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product E				t Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Versio	n	Manufacturing Site		V	Weight*	UOM	Unit Type	
	NCP1377			BPG ANA PWM CURRNT MODE CNTRL			2023-06-08 PH1			4	71.68	mg	Each			
	cturing Process Informa		Terminal Base	Alloy	-STD-020 MSL	Pating	Dook Proof	ass Pady	Tamparati	uro May T	ima at Baak '	Tamparati	ura Numb	or of Poflow Cv	olos	
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RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.19	mg	Supplier	Silicon (Si)	7440-21-3		2.19	mg
Die Attach	8.92	mg	Supplier	Silver (Ag)	7440-22-4		6.69	mg
			Supplier	Epoxy resins	129915-35-1		2.23	mg
Lead Frame	131.05	mg	Supplier	Silver (Ag)	7440-22-4		0.9173	mg
			Supplier	Zinc (Zn)	7440-66-6		0.2621	mg
			Supplier	Iron (Fe)	7439-89-6		3.4073	mg
			Supplier	Copper (Cu)	7440-50-8		126.4632	mg
Mold Compound-Black	317.53	mg		Epoxy Phenol Resin	proprietary data		33.3406	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		284.1893	mg
Plating	11.9	mg	Supplier	Tin (Sn)	7440-31-5		11.9	mg
Wire Bond	0.09	mg	Supplier	Palladium (Pd)	7440-05-3		0.0009	mg
			Supplier	Copper (Cu)	7440-50-8		0.0891	mg